

Technical Data Sheet

5mm Snapled

5C-03-B81-Y7C-A3U1V1FN-AM

Lead (Pb) Free Product - RoHS Compliant



Feature

- Colorless clear resin.
- Low thermal resistance
- Packaged in tubes for Automatic Insertion Equipment.
- Total Flux: 11250 to 22500 mlm at 150mA.
- Qualification according to AEC-Q101.

Applications

- Automotive exterior lighting: Turn light, rear-view mirror light, side light, license light switch,...etc.
- Electronic signs and signals
- General lighting application

Device Selection Guide

Chip	Emitted Color	Resin Color
Material		
AlGaInP	Yellow	Water Clear

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Absolute Maximum Ratings (Ta=25)

Parameter	Symbol	Rating	Unit
Reverse Voltage	V _R	5	V
Forward Current	I _F	150	mA
Peak Forward Current (Duty 1/10 @1KHz)	I _{FP}	200	mA
Power Dissipation	P _d	400	mW
Operating Temperature	T _{opr}	-40 ~ +100	
Storage Temperature	T _{stg}	-40 ~ +100	
Junction Temperature	T _j	120	
Thermal Resistance	R _{th J-A}	100	/W
ESD (Classification acc. AEC Q101)	ESD _{HBM}	4000	V
	ESD _{MM}	200	V
Soldering Temperature	T _{sol}	Wave Soldering : 260 Hand Soldering : 350	for 5 sec. for 3 sec.

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Electro-Optical Characteristics (Ta=25)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Total Flux	Φ_V	11250	---	22500	mlm	$I_F = 150\text{mA}$
Viewing Angle	$2\theta_{1/2}$	---	85	---	deg	$I_F = 150\text{mA}$
Peak Wavelength	λ_p	----	594	----	nm	$I_F = 150\text{mA}$
Dominant Wavelength	λ_d	586	----	598	nm	$I_F = 150\text{mA}$
Spectrum Radiation Bandwidth	$\Delta\lambda$	---	16	---	nm	$I_F = 150\text{mA}$
Forward Voltage	V_F	1.7	---	2.9	V	$I_F = 150\text{mA}$
Reverse Current	I_R	---	---	10	μA	$V_R = 5\text{V}$

Note:

1. Tolerance of Total Flux: $\pm 11\%$
2. Tolerance of Dominant Wavelength: $\pm 1\text{nm}$
3. Tolerance of Forward Voltage: $\pm 0.1\text{V}$

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Bin Range of Forward Voltage (Ta=25)

Bin Code	Min.	Max.	Unit	Condition
A	1.7	1.9	V	I _F =150mA
B	1.9	2.1		
C	2.1	2.3		
D	2.3	2.5		
E	2.5	2.7		
F	2.7	2.9		

Note:

Tolerance of Forward Voltage: ±0.1V

Bin Range of Dominant Wavelength (Ta=25)

Bin Code	Min.	Max.	Unit	Condition
1	586	590	nm	I _F =150mA
2	590	594		
3	594	598		

Note:

Tolerance of Dominant Wavelength: ±1nm



EVERLIGHT ELECTRONICS CO., LTD.

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Bin Range of Total Flux (Ta=25)

Bin Code	Min.	Max.	Unit	Condition
U1	11250	14250	mlm	I _F =150mA
U2	14250	18000		
V1	18000	22500		

Note:

Tolerance of Total Flux: ±11%



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Typical Electro-Optical Characteristics Curves

Typical Curve of Spectral Distribution

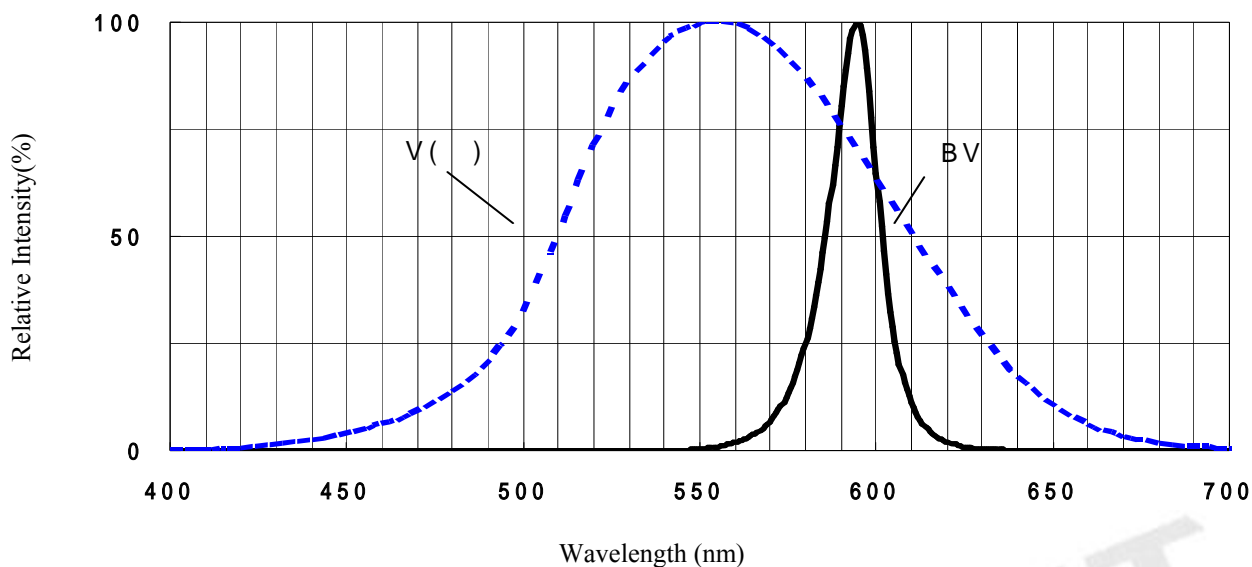
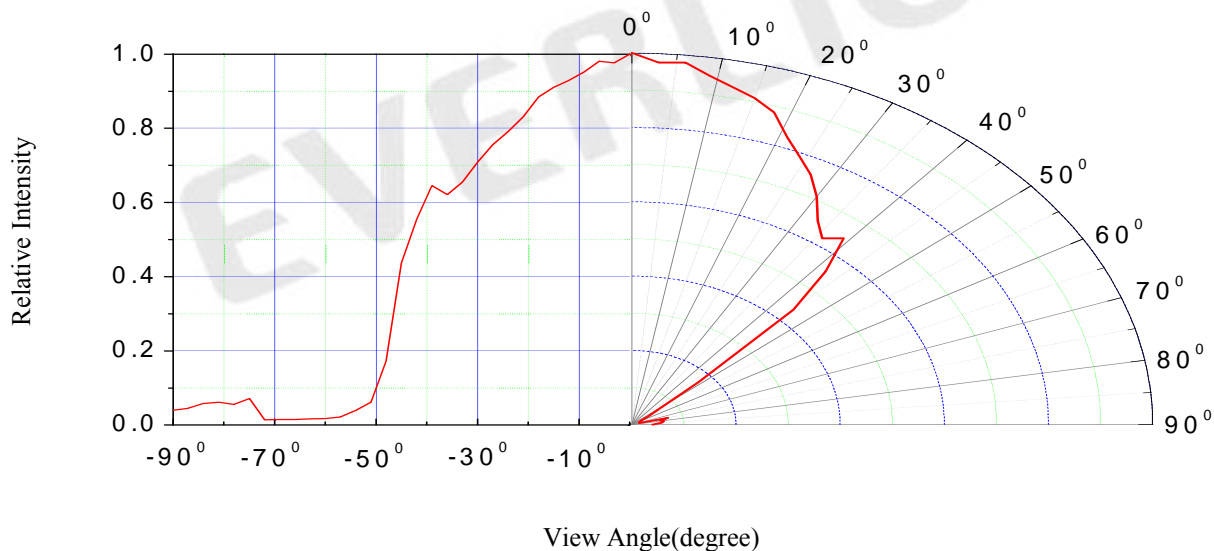


Diagram Characteristics of Radiation

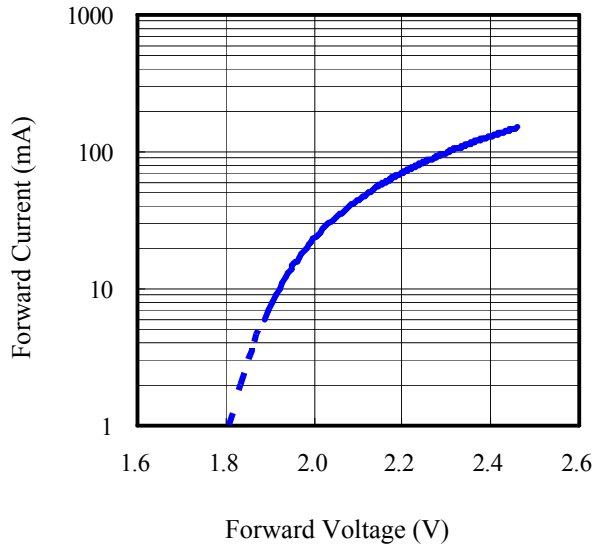


Technical Data Sheet

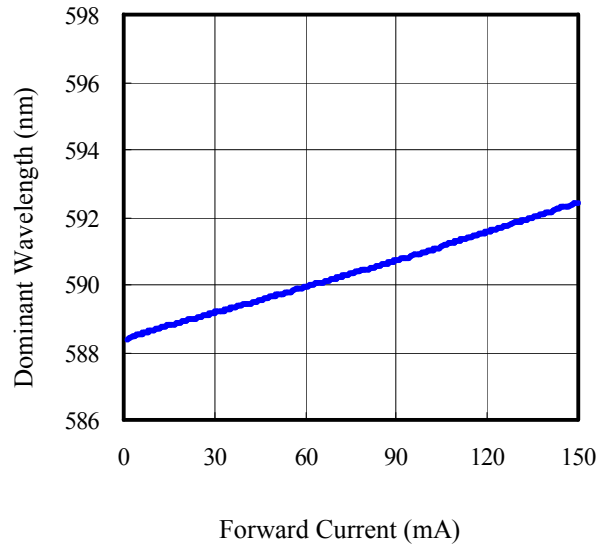
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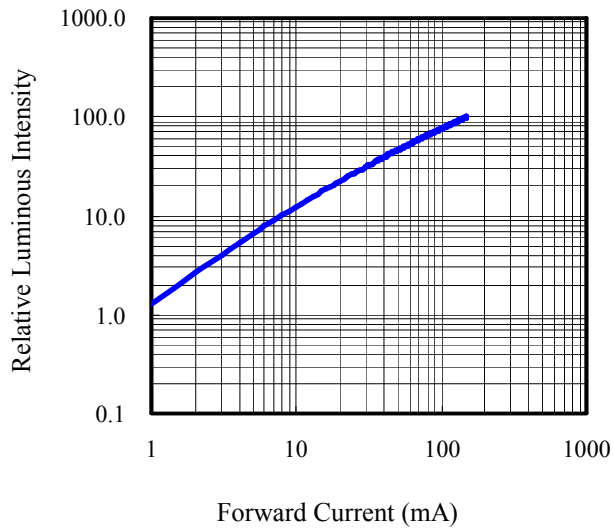
Forward Current vs. Forward Voltage
($T_a=25^\circ\text{C}$)



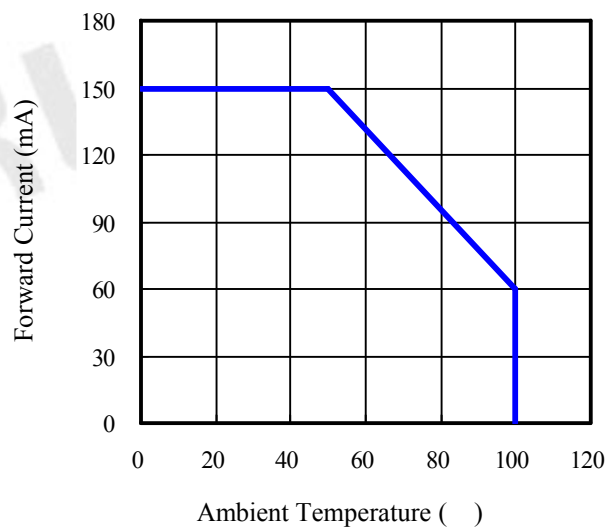
Dominant Wavelength vs. Forward Current
($T_a=25^\circ\text{C}$)



Relative Luminous Flux vs. Forward Current
($T_a=25^\circ\text{C}$)



Max. Permissible Forward Current vs. Ambient Temperature

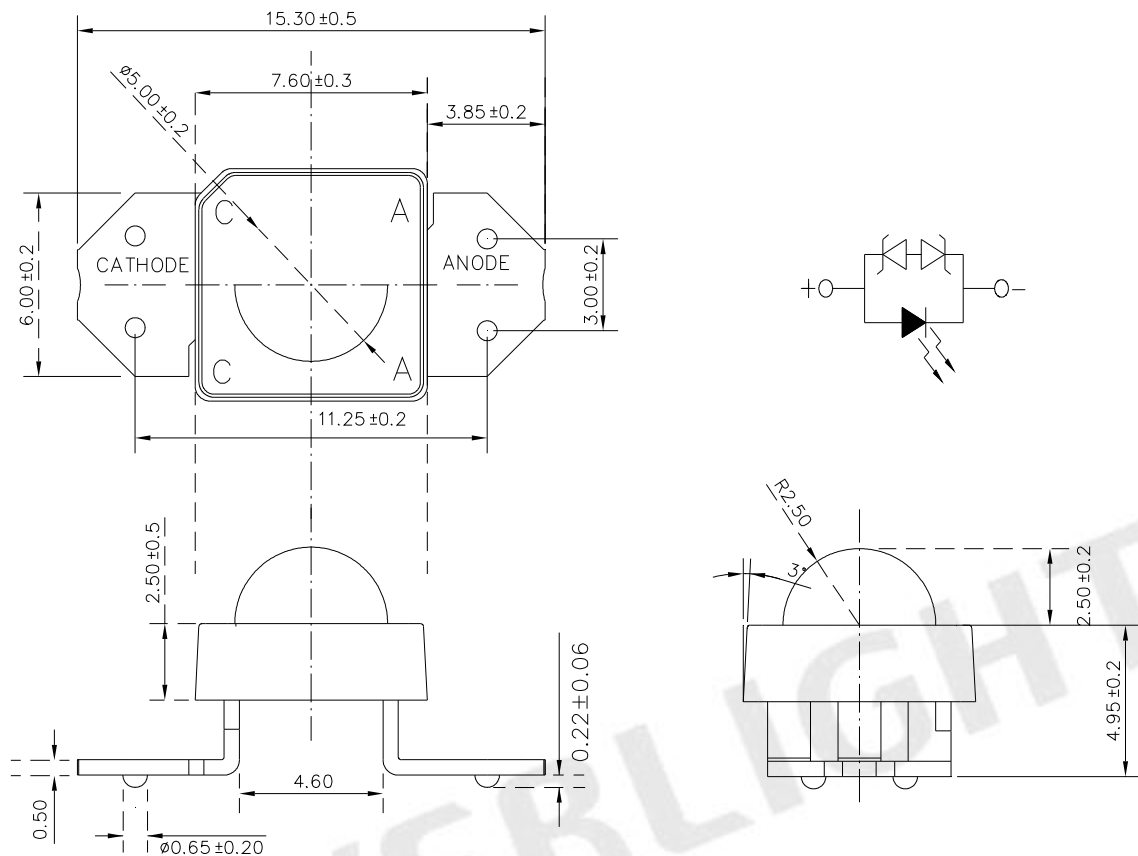


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Package Dimension



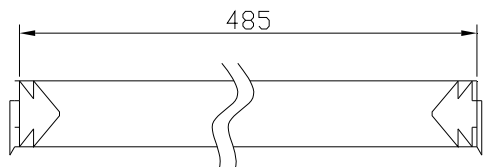
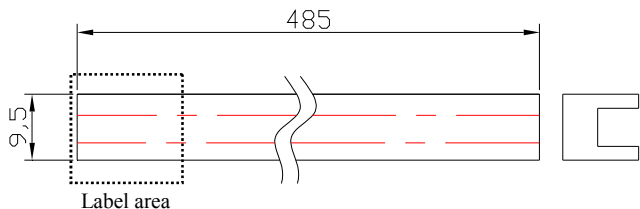
- Notes:**
1. An epoxy meniscus may extend about 1.5mm(0.059") up/down the leads
 2. Tolerances unless dimensions ± 0.25 mm
 3. All dimensions are in millimeters

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**Moisture Resistant Packing Materials
Tube**



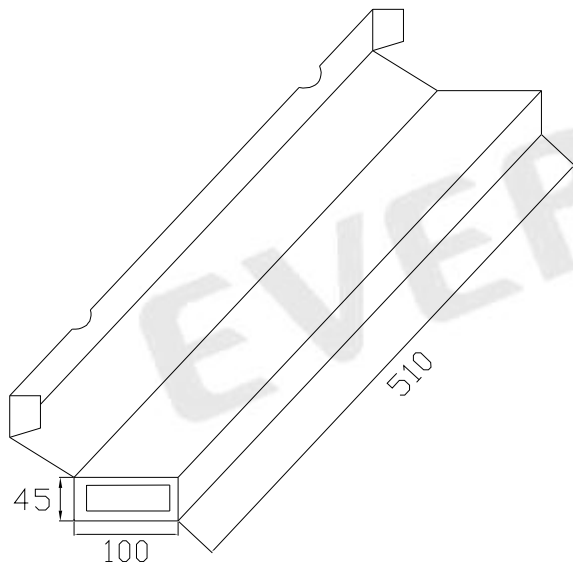
Note: Tolerances unless mentioned ± 2.0 mm. Unit = mm

EVERLIGHT	PART NO:	QTY:
	LOT NO:	CAT:

Tube Label Explanation

- PART NO: Product Number
- QTY: Packing Quantity
- LOT No: Lot Number
- CAT: Rank of (VF)(Note*)(Φ V)
Note: λ_d /CIE/Color temperature

Standard Box



Tube Label Explanation

- CPN: Customer's Product Number
- P/N: Product Number
- QTY: Packing Quantity
- CAT: Rank of (VF)(Note*)(Φ V)
Note: λ_d /CIE/Color temperature
- HUE/REF: Reference
- LOT No: Lot Number

Note: Tolerances unless mentioned ± 3.0 mm. Unit = mm

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Packing Quantity

Packing material	Length × Width × height (mm)	Tube Quantity (Pcs)	LED Quantity (Pcs)
Tube	485 x 9.5 x 14.8	1	60
Standard box	510 x 100 x 45	15	900
Large box	510 x 150 x 90	12	10800

Note:

1. Normal packing specification is use standard box, unless already defined initially.
2. Vacuum packing with anti-static bag after packing in standard box.
3. Specifications are subject to change without prior notice.

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Notes

1. Lead Forming

- During lead formation, the leads should be bent at a point at least 3mm from the base of the epoxy bulb.
- Lead forming should be done before soldering.
- Avoid stressing the LED package during leads forming. The stress to the base may damage the LED's characteristics or it may break the LEDs.
- Cut the LED leadframes at room temperature. Cutting the leadframes at high temperatures may cause failure of the LEDs.
- When mounting the LEDs onto a PCB, the PCB holes must be aligned exactly with the lead position of the LED. If the LEDs are mounted with stress at the leads, it causes deterioration of the epoxy resin and this will degrade the LEDs.

2. Storage

- The LEDs should be stored at 30°C or less and 70%RH or less after being shipped from Everlight and the storage life limits are 3 months. If the LEDs are stored for 3 months or more, they can be stored for a year in a sealed container with a nitrogen atmosphere and moisture absorbent material.
- Please avoid rapid transitions in ambient temperature, especially, in high humidity environments where condensation can occur.

3. Soldering

- Careful attention should be paid during soldering. Solder the LED no lower than 1.6mm from the base of stopper is recommended.
- Avoiding applying any stress to the lead frame while the LEDs are at high temperature particularly when soldering.
- Recommended soldering conditions:

Hand Soldering		DIP Soldering	
Temp. at tip of iron	300 Max. (30W Max.)	Preheat temp.	100 Max. (60 sec Max.)
Soldering time	3 sec Max.	Bath temp.	260 Max.
Distance	No lower than 1.6mm from the base of stopper	Bath time.	5 sec Max.

- Dip and hand soldering could just be done no more than twice.
- After soldering the LEDs, the epoxy bulb should be protected from mechanical shock or

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vibration until the LEDs return to room temperature.

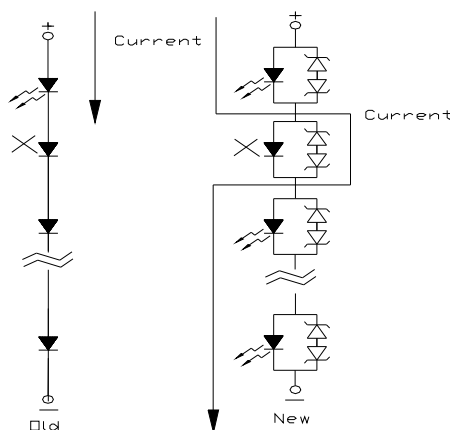
- A rapid-rate process is not recommended for cooling the LEDs down from the peak temperature.
- Although the recommended soldering conditions are specified in the above table, dip or handsoldering at the lowest possible temperature is desirable for the LEDs.
- Wave soldering parameter must be set and maintain according to recommended temperature and dwell time in the solder wave.

4. Cleaning

- When necessary, cleaning should occur only with isopropyl alcohol at room temperature for a duration of no more than one minute. Dry at room temperature before use.
- Do not clean the LEDs by the ultrasonic. When it is absolutely necessary, the influence of ultrasonic cleaning on the LEDs depends on factors such as ultrasonic power and the assembled condition. Ultrasonic cleaning shall be pre-qualified to ensure this will not cause damage to the LED

5. Circuit Protection

- Below the zener reference voltage V_z , all the current flows through LED and as the voltage rises to V_z , the zener diode "breakdown." If the voltage tries to rise above V_z current flows through the zener branch to keep the voltage at exactly V_z .
- When the LED is connected using serial circuit, if either piece of LED is no light up but current can't flow through causing others to light down. In new design, the LED is parallel with zener diode. if either piece of LED is no light up but current can flow through causing others to light up.



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6. Heat Management

- Heat management of LEDs must be taken into consideration during the design stage of LED application. The current should be de-rated appropriately by referring to the de-rating curve found in each product specification.
- The temperature surrounding the LED in the application should be controlled. Please refer to the data sheet de-rating curve.

7. ESD (Electrostatic Discharge)

- Electrostatic discharge (ESD) or surge current (EOS) can damage LEDs.
- An ESD wrist strap, ESD shoe strap or antistatic gloves must be worn whenever handling LEDs.
- All devices, equipment and machinery must be properly grounded.
- Use ion blower to neutralize the static charge which might have built up on surface of the LEDs plastic lens as a result of friction between LEDs during storage and handing.

8. Other

- Above specification may be changed without notice. EVERLIGHT will reserve authority on material change for above specification.
- When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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